



Dimensions

Footprint	7343
L	7.3mm +/-0.3mm
W	4.3mm +/-0.3mm
H	2mm MAX
S	1.3mm +/-0.3mm
F	2.4mm +/-0.1mm
K	1.7mm TYP

Packaging Specifications

Packaging	T&R, 330mm
Packaging Quantity	3750

General Information

Dielectric	MnO ₂ Tantalum
Style	SMD Chip
Description	SMD, Molded, Low Profile, Low ESR, Surge Robust
Features	Low Profile, Low ESR, Surge Robust
RoHS	Yes
Termination	Tin
AEC-Q200	No
Notes	Obsolete. Old Part Number [Obsolete] Was B45194R1337K406.

Specifications

Capacitance	330 uF
Capacitance Tolerance	10%
Voltage DC	6.3 VDC (85C), 4.22 VDC (125C)
Temperature Range	-55/+125°C
Rated Temperature	85°C
Dissipation Factor	8%
Failure Rate	N/A
ESR	0.15 Ohms (100kHz)
Ripple Current	910 mAmps (25C), 819 mAmps (85C), 364 mAmps (125C)
Leakage Current	20.8 uA